

100V, 5A, Synchronous Buck Control

1 Features

- 12V to 100V wide operating input range
- 5A continuous output current capability
- Integrated 120V, 17mΩ high side and 120V, 17mΩ low side power MOSFET switches
- Adjustable Frequency from 50kHz to 500kHz Operation
- Precision Reference Voltage (1.2 V)
- Programmable Soft-Start with Pre-biased Load Capability
- Programmable EN Off Delay Function
- Programmable Over-Load Protection with 0.2s blank timer and Hiccup
- Programmable Cycle-by-Cycle Current Limiting Protection
- Programmable Input Under-Voltage Lockout Protection with Latch
- Programmable Input Over-Voltage Protection with Latch
- Output Over-Voltage Protection
- Over-Temperature Protection
- QFN6*6mm-48L

2 Applications

- 48 V Non-Isolated DC-DC Converter
- Car applications
- Telecom Bus Converters
- General purpose
- USB Type-C Power Delivery
- Industrial DC-DC Motor Drivers

3 Description

PL8905 is a high voltage Buck Control designed for high performance synchronous Buck DC/DC applications with input voltages up to 100V.

PL8905 integrates a high efficiency synchronous step-down switching regulator, which includes a 120V, 17m Ω high side and a 120V, 17m Ω low side MOSFETs to provide 5A continuous load current over 12V to 100V wide operating input voltage.

PL8905 switching frequency is programmable from 50 kHz up to 500 kHz allowing the flexibility to tune for efficiency and size. The output voltage can be precisely regulated using the internally 1.2 V reference voltage for low voltage applications.

Protection features include user programmable under voltage lockout, over voltage lockout and over current protection. The supply current drops below 10µA in shutdown mode. PL8905 is a good choice for car infotainment application, telecom bus converter, etc.

4 Typical Application Schematic

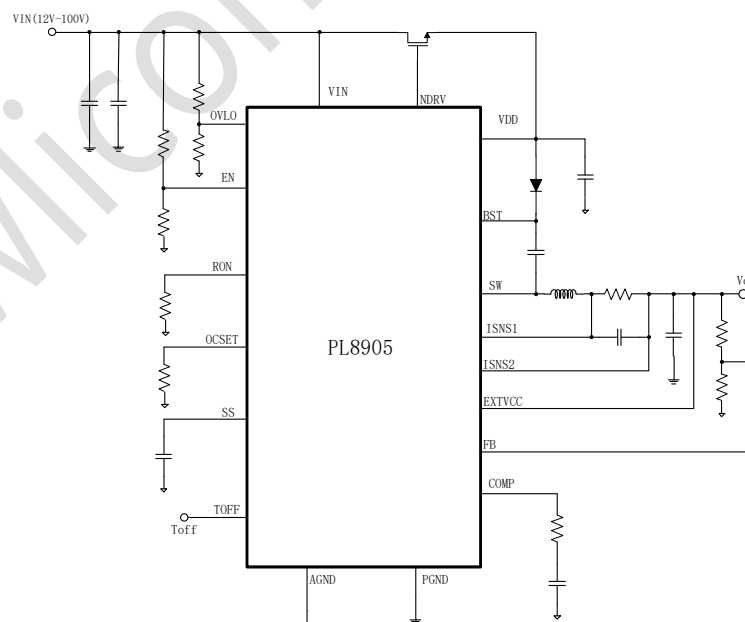
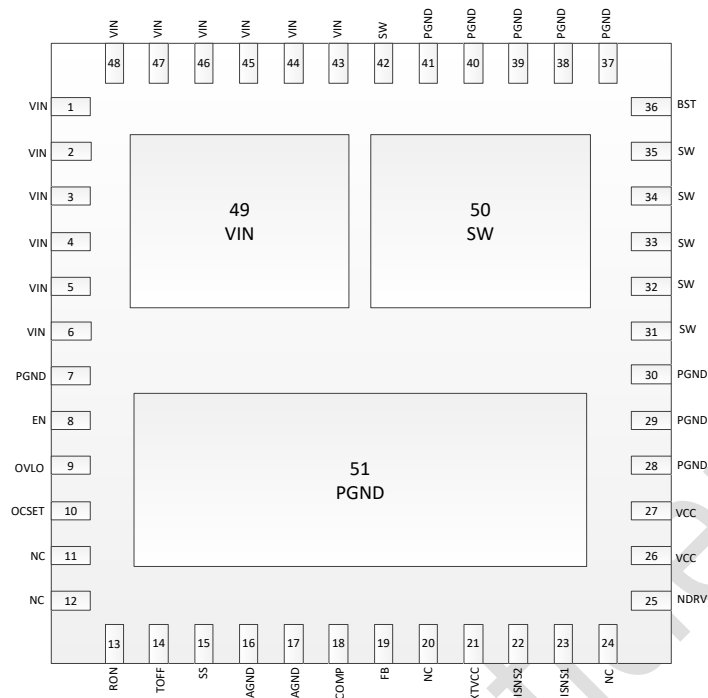


Fig. 1 Application Schematic



Pin		Description
Name	Number	
VIN	1,2,3,4,5,6, 43,44,45,46,47, 48,49	Input voltage.
EN	8	Enable pin.
OVLO	9	An external voltage divider is used to set the over voltage threshold levels.
OCSET	10	Current limit set point. A resistor from this pin to GND will set the positive and negative current limit threshold.
RON	13	Connect this pin to GND by a resistor to set the switching frequency.
TOFF	14	This pin provides user programmable shutdown delay time function. Connect to GND: No Delay Connect to VCC: 20s Floating: 10s
SS	15	This pin provides user programmable soft-start function. External capacitor connected from this pin to ground sets the startup time of the output voltage.
AGND	16,17	Signal ground for internal reference and control circuitry.
COMP	18	Output of error amplifier. An external resistor and capacitor network is typically connected from this pin to ground to provide loop compensation.
FB	19	Feedback Input. FB senses the output voltage. Connect FB with a resistor divider connected between the output and ground. FB is a sensitive node. Keep FB away from noisy signal, such as SW and BST pin.
EXTVCC	21	External Power Input to an Internal LDO linear regulator Connected to VCC. This LDO supplies VCC power from EXTVCC, bypassing the external NDRV LDO whenever EXTVCC is higher than 10V. Do not exceed 30V on this pin. Do not connect EXTVCC to a voltage greater than VIN. Connect to GND if not used.
ISNS2	22	Inductor current sense input 2.
ISNS1	23	Inductor current sense input 1.
NDRV	25	Drive Output for External Pass Device of the NDRV LDO Linear Regulator for VCC. Connect this pin to the gate of an external NMOS or NPN pass device.
VCC	26,27	This pin provides power for the internal blocks of the IC. A minimum of 4.7uF capacitor must be connected from this pin to ground.
SW	31,32,33,34,35.	Switch Node. Connect this pin to the switching node of inductor.

	42,50	
BST	36	This pin powers the high side driver and must be connected to a voltage higher than input voltage. A minimum of 0.1uF, high frequency capacitor must be connected from this pin to switch node.
PGND	7,28,29,30, 37,38,39, 40,41,51	Power Ground. This pin serves as a separate ground for the MOSFET driver and should be connected to the system's power ground plane.
NC	11,12,20,24	Not Connected.

6 Device Marking Information

Part Number	Order Information	Package	Package Qty	Top Marking
PL8905	PL8905IQN48	QFN6x6 - 48	2500	8905 RAAYMD

PL8905: Part Number

RAABB: Lot Number. R: Year; AABB: Manufacturing Code

7 Specifications

7.1 Absolute Maximum Ratings^(Note1)

	PARAMETER	MIN	MAX	Unit
Input Voltages	V _{IN} to GND	-0.3	100	V
	V _{FB} , V _{OVLO} , V _{UVLO} to GND	-0.3	6	
	V _{TOFF} to GND	-0.3	12	
	V _{ISNS1,2} to GND	-0.3	65	
	V _{EN} to GND	-0.3	100	
	V _{EXTVCC} to GND	-0.3	30	
Output Voltages	V _{VDD} to GND	-0.3	12	V
	V _{RON} , V _{OCSET} , V _{SS} , V _{COMP} to GND	-0.3	6	
	V _{BST} to V _{SW}	-0.3	12	
	V _{SW} to GND	-3	V _{IN} + 0.3	

7.2 Handling Ratings

PARAMETER	DEFINITION	MIN	MAX	UNIT
T _{ST}	Storage Temperature Range	-65	150	°C
T _J	Junction Temperature		+150	°C
T _L	Lead Temperature		+260	°C
V _{ESD}	HBM Human body model		2	kV
	CDM Charger device model		500	V

7.3 Recommended Operating Conditions^(Note 2)

	PARAMETER	MIN	MAX	Unit
Input Voltages	V _{IN} to GND	12	100	V
	V _{FB} , V _{OVLO} , V _{UVLO} to GND	-0.3	5	
	V _{TOFF} to GND	-0.3	10	
	V _{ISNS1,2} to GND	-0.3	60	
	V _{EN} to GND	-0.3	100	
	V _{EXTVCC} to GND	-0.3	30	
Output Voltages	V _{VDD} to GND	-0.3	10	V
	V _{RON} , V _{OCSET} , V _{SS} , V _{COMP} to GND	-0.3	5	
	V _{BST} to V _{SW}	-0.3	10	
	V _{SW} to GND	-3	V _{IN} +0.3	
Temperature	Operating junction temperature range, T _J	-40	+125	°C

7.4 Thermal Information(Note 4)

Symbol	Description	ETSSOP-20	Unit
θ _{JA}	Junction to ambient thermal resistance	40	°C/W
θ _{JC}	Junction to case thermal resistance	23	

Notes:

- 1) Exceeding these ratings may damage the device.
- 2) The device function is not guaranteed outside of the recommended operating conditions.
- 3) Measured on approximately 1" square of 1 oz copper.

7.5 Electrical Characteristics(Typical at $V_{in} = 12V$, $T_J = 25^\circ C$, unless otherwise noted.)

SYMBOL	PARAMETER	CONDITION	MIN	TYP	MAX	UNIT
VIN	Input Supply Operating Voltage Range		12		100	V
VOUT	Regulated Output Voltage Set Point		1.2		60	V
MOSFET						
RDS(ON)_H	High-Side Switch On-Resistance	IOUT = 1A, VOUT = 5V		17		mΩ
RDS(ON)_L	Low-Side Switch On-Resistance	IOUT = 1A, VOUT = 5V		17		mΩ
REFERENCE VOLTAGE						
IQ	Statics Current	Open Loop, VFB = 1.25V, No Switching, VIN=48V , TJ=25°C		400		uA
ISHUTDOWN	EN Shutdown Supply Current	Close Loop, VEN=0V, VIN=48V		20		
REFERENCE VOLTAGE						
VFB	Feedback Voltage			1.2		V
	Accuracy		-1.5		+1.5	%
SUPPLY VOLTAGE (Vcc)						
VDD	VDD Regulator Output	Supply by NDRV LDO	9	9.5	10	
		Supply by EXTVCC LDO	9.5	10	10.5	
UNDERVOLTAGE LOCKOUT						
VDD_UVLO	VDD Under Voltage Lockout Voltage(VDD increasing)	-40°C≤ TJ≤ 125°C		8		V
VDD_UVLOH	VDD Under Voltage Hysteresis			670		mV
VBST_UVLO	VBST Under Voltage Lockout Voltage(VBST increasing)	-40°C≤ TJ≤ 125°C		5.6		V
VBST_UVLO_H	VBST Under Voltage Hysteresis			860		mV
VIN_UVLO	VIN Under Voltage Lockout Voltage(VIN increasing)			6.5		V
VIN_UVLOH	VIN Under Voltage Hysteresis			650		mV
VEN_UVLO	EN Under Voltage Lockout Voltage(VEN increasing)			1.2		V
VEN_UVLOH	EN Under Voltage Hysteresis			200		mV
OVER VOLTAGE LOCKOUT						
REFIN_OVP	Reference of VIN Over Voltage Lockout Voltage(VIN increasing)			1.2		V
HYSIN_OVP	Reference Hysteresis of VIN Over Voltage Lockout Voltage			200		mV
CONTROL LOOP						
I(Source/Sink)	Source/Sink Current			300		uA
gm	Trans-conductance			3		mS
SOFT-START						
ISS	Soft-Start Current	SS = 0 V	15	20	25	uA
VSNS LIMIT						
VOCSET	OCSET voltage	-40°C≤ TJ≤ 125°C		1.2		V
VLIMH	On Duty ISNS1-ISNS2 Limit	ROCSET = 25k Ohm, VLIMH=1.2/ROCSET*25K/10		120		mV
VLIML	Off Duty ISNS1-ISNS2 Limit	ROCSET = 25k Ohm, VLIML=1.2/ROCSET*20K/10		96		mV
TOVERLOAD	Over Load Protection Blank Time			200		ms
Frequency						
Fsw	Switching Frequency	Fsw=Vout/(Rh*500p) Or Fsw=1/(RL*50p)	50	200	500	kHz

TON _{MIN}	Minimum On Time		140	ns
TOFF _{MIN}	Minimum Off Time		400	ns
Toff Timer				
T _{OFF}	Toff Time Delay	Toff = GND	0	s
		Toff = Float	10	s
		Toff = VCC	20	s
OUTPUT DRIVERS				
Tdelay1	Top Gate Off to Bottom Gate On Delay		70	ns
Tdelay2	Bottom Gate Off to Top Gate On Delay		70	ns

Note:

4) Guaranteed by design, not tested in production.

8.3 Feature Description

8.3.1 Enable and OVLO

When the EN pin is pulled high above 1.2V, this part is enabled. When the EN pin is pulled below 1.0V, this part goes into the shutdown mode and stops operation.

When the OVLO pin is pulled high above 1.2V, the PL8905 is disabled and it will not resume switching even if OVLO falls below 1.0V unless EN is toggled.

8.3.2 Under-voltage Lockout

This controller stops switching when the input voltage drops below 5.85V or VDD is below 7.33V. It resumes operation when input voltage is larger than 6.5V and VDD is larger than 8V.

8.3.3 Cycle-by-Cycle Current Limit and Over Load Protection

The PL8905 provides cycle-by-cycle current limit to protect power MOSFET during on duty and also off duty. It will immediately turn off high side MOSFET once on duty current limit is triggered or prolongs the off duty until the inductor current is lower than off duty current limit. Hiccup protection will be triggered if the over current condition endures more than 200ms. And the switching will be resumed after 16 soft start procedures.

8.3.4 Programmable Switching Frequency

This controller features a programmable switching frequency ranging from 50kHz to 500kHz.

The frequency setting by RON is calculated as below:

$$F_{SW} = \frac{V_{OUT}}{R_{ON} (k\Omega) \times 0.5} (\text{MHz}) \quad (1)$$

8.3.5 Error Amplifier

The PL8905 has a trans-conductance amplifier and compares the feedback voltage with the internal voltage reference (or the internal soft start voltage during startup phase). The trans-conductance of the error amplifier is 3 mA / V typically. The loop compensation components are required to be placed between the COMP terminal and ground to balance the loop stability and the transient response time.

8.3.6 VCC Regulators

The PL8905 contains two VDD regulators that provide power supply for low side gate driver and boot-strap high side gate drive. One is the NDRV regulator which regulates VDD to 9.5V. The other one is the 10V low dropout LDO powered by EXTVCC which is current limited to 60mA. The VDD load current should be evaluated if NDRV regulator is not used.

8.3.7 Bootstrap Voltage (BST)

The PL8905 has an integrated bootstrap regulator, and requires a small ceramic capacitor between the BST pin and SW pin to provide the gate drive voltage for the high-side FET. The bootstrap capacitor is charged when the BST-SW voltage is below regulation. The value of this ceramic capacitor should be above 100 nF. A ceramic capacitor with an X7R or X5R grade dielectric with a voltage rating of 25 V or higher is recommended because of the stable characteristics over temperature and DC biased voltage.

8.3.8 Thermal Shutdown

A thermal shutdown is implemented to prevent the damage due to the excessive heat and power dissipation. Typically, the thermal shutdown occurs at the junction temperature exceeding 150°C. When the thermal shutdown is triggered, the device stops switching and recover when the junction temperature falls below 130°C.

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9 Application and Implementation

9.1 Setting the switching Frequency

The switching frequency of the PL8905 can be programmed as equation 1. For a target switching frequency of 200 kHz, The calculated value is 120 kΩ.

9.2 Setting the Output Current Limit

The cycle-by-cycle current limit of the PL8905 is configured by combination of Rocset between OCSET and AGND and sense resistor Rsns in serial with inductor. The cycle-by-cycle current limit is determined as follows:

$$I_{LIML} = \frac{2.4}{R_{OCSET} (k\Omega) \times R_{SNS} (\Omega)} (A) \quad (2)$$

9.3 Setting the Output Voltage

Choose R1 and R2 to program the proper output voltage. To minimize the power consumption under light load, it is desirable to choose large resistance values for both R1 and R2. A value between 10k and 1M is recommended for both resistors. If R1=200k is chosen, then R2 can be calculated to be:

$$V_{OUT} = V_{FB} \times \left(1 + \frac{R_1}{R_2}\right) \quad (3)$$

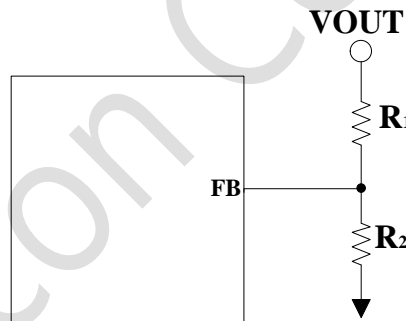


Fig. 4

9.4 Selecting the Inductor

1) Choose the inductance to provide the desired ripple current. It is suggested to choose the ripple current to be about 40% of the maximum average input current. The inductance is calculated as:

$$L = \frac{V_{OUT}}{V_{IN}} \times \frac{V_{IN} - V_{OUT}}{0.4 \times F_{SW} \times I_{OUT_MAX}} \quad (4)$$

where F_{SW} is the switching frequency and I_{OUT_MAX} is the maximum load current.

PL8905 is less sensitive to the ripple current variations. Consequently, the final choice of inductance can be slightly off the calculation value without significantly impacting the performance.

2) The saturation current rating of an inductor must be selected to guarantee an adequate margin to the peak inductor

current under full load conditions.

3) The DCR of the inductor and the core loss at the switching frequency must be low enough to achieve the desired efficiency requirement. It is desirable to choose an inductor with $DCR < 10\text{m}\Omega$ to achieve a good over-all efficiency.

9.5 Selecting the Output Capacitors

The Output capacitor is selected to handle the output ripple noise requirements. Both steady state ripple and transient requirements must be taken in to account when selecting these capacitors. For the best performance, it is recommended to use X5R or better grade ceramic capacitor.

9.6 Selecting the Input Capacitors

Multilayer ceramic capacitors are an excellent choice for the input decoupling of the step-down converter as they have extremely low ESR and are available in small footprints. Input capacitors should be located as close as possible to the device. While a $10\text{-}\mu\text{F}$ input capacitor is sufficient for the most applications, larger values may be used to reduce input current ripple.

Take care when using only ceramic input capacitors. When a ceramic capacitor is used at the input and the power is being supplied through long wires, such as from a wall adapter, a load step at the output can induce ringing at the VIN pin. This ringing can couple to the output and be mistaken as loop instability or could even damage the part. Additional "bulk" capacitance (electrolytic or tantalum) in this circumstance, should be placed between CIN and the power source lead to reduce ringing that can occur between the inductance of the power source leads and CIN.

9.7 Selecting the Bootstrap Capacitor

The bootstrap capacitor between the BST and SW pin supplies the gate current to charge the high-side FET device gate during each cycle's turn-on and also supplies charge for the bootstrap capacitor. The recommended value of the bootstrap capacitor is $0.1\text{-}1\text{-}\mu\text{F}$. CBST should be a good quality, low ESR, ceramic capacitor located at the pins of the device to minimize potentially damaging voltage transients caused by trace inductance. A value of $0.1\text{-}\mu\text{F}$ was selected for this design example.

9.8 Selecting the VCC Capacitors

The primary purpose of the VCC capacitor is to supply the peak transient currents of the driver and bootstrap capacitor as well as provide stability for the VCC regulator. The value of CVCC should be at least 10 times greater than the value of CBST, and should be a good quality, low ESR, ceramic capacitor. CVCC should be placed close to the pins of the IC to minimize potentially damaging voltage transients caused by the trace inductance. A value of $4.7\text{-}\mu\text{F}$ was selected for this design example.

The Figure 5 is the typical application schematic for 36 to 90-V input to output 12-V output converter.

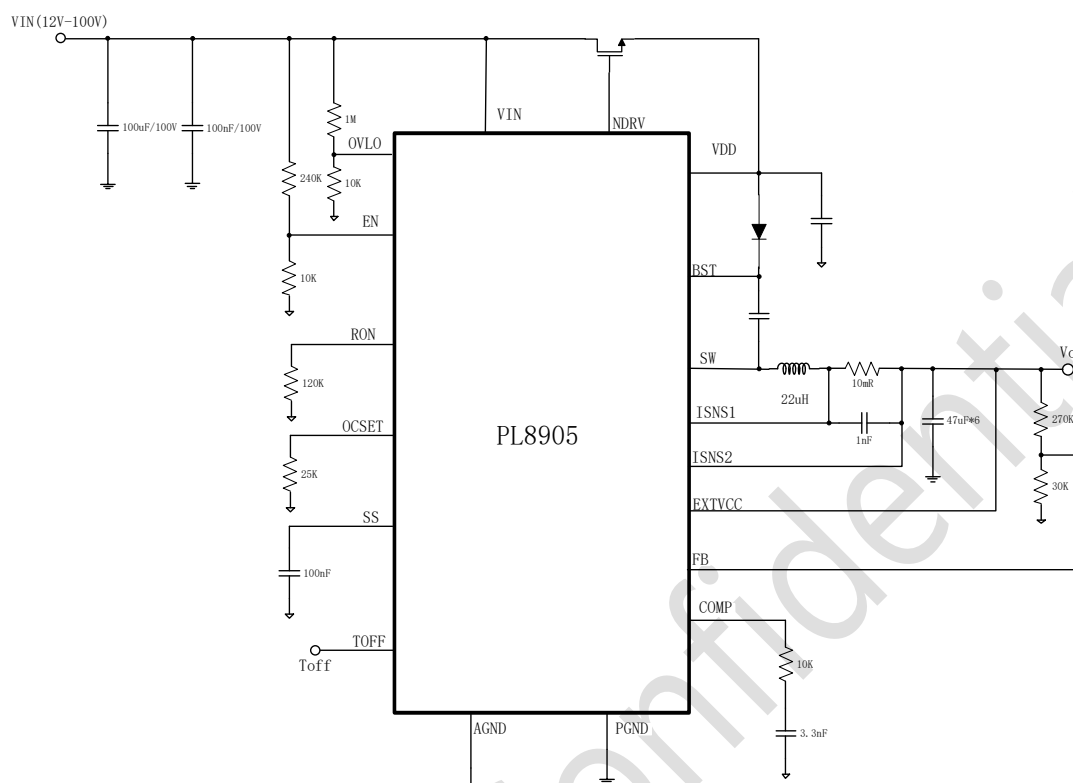
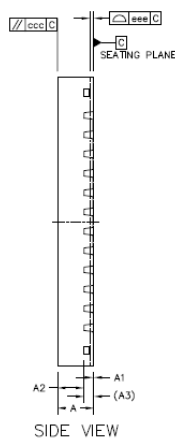
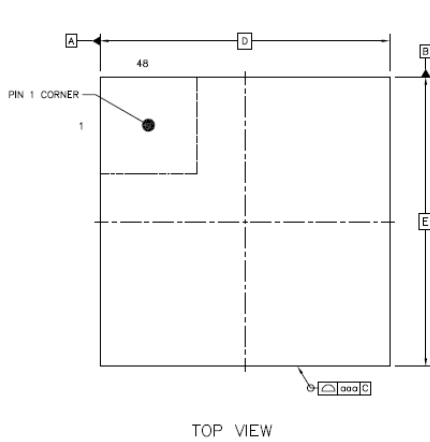
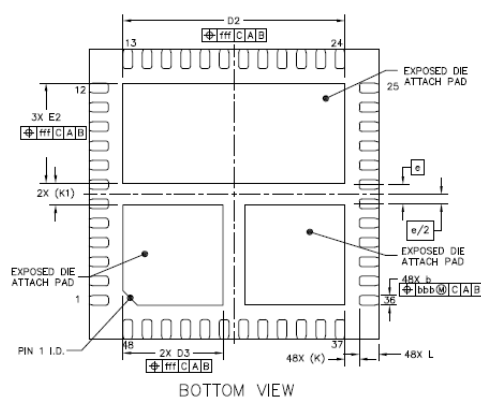


Figure 5. Application Schematic

10 Packaging Informatio



	SYMBOL	MIN	NOM	MAX
TOTAL THICKNESS	A	0.7	0.75	0.8
STAND OFF	A1	0	0.02	0.05
MOLD THICKNESS	A2	---	0.55	---
L/F THICKNESS	A3	0.203 REF		
LEAD WIDTH	b	0.15	0.2	0.25
BODY SIZE	X	6 BSC		
	Y	6 BSC		
LEAD PITCH	e	0.4 BSC		
EP SIZE	X	D2	4.5	4.6
	Y	D3	1.975	2.075
LEAD LENGTH	X	E2	1.975	2.075
	Y	L	0.3	0.4
LEAD TIP TO EXPOSED PAD EDGE	K	0.3 REF		
PAD TO PAD	K1	0.45 REF		
PACKAGE EDGE TOLERANCE	aaa	0.1		
MOLD FLATNESS	ccc	0.1		
COPLANARITY	eee	0.08		
LEAD OFFSET	bbb	0.07		
EXPOSED PAD OFFSET	fff	0.1		



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